

REMARKS

The drawings of this application were objected to as failing to comply with 37 CFR 1.84(p)(5) because they do not include reference “34”, and instead seem to include “39” not mentioned in the specification.

Although the numeral 34 should have appeared in Figure 3, applicant’s attorney has adopted the Examiner’s suggestion that the number 34 occurring at page 5 of the specification be twice changed to 39 so as to agree with the “metal tip 39” of Figure 3.

Our claims 4-6 and 15-17 were objected to because of the format “material: thickness”, and the Examiner indicated that applicant should amend these claims to definitively recite the claimed layers’ thickness and composition without using a colon. Appropriate correction has now been made.

Claims 1-22 was rejected under 35 U.S.C. 112, second paragraph, as being indefinite. In particular, the Examiner indicated that the claims recite “microdendritic” features and pad arrays. The Examiner felt that the term “microdendritic” in claims 1-22 is a relative term that renders the claims indefinite.

The Examiner later indicated that applicant should either show prior art detailing the formation of “microdendritic” features or amend to recite the “dendritic” features.

The Examiner is thanked for his suggestion of amending to recite “dendritic,” and this has been done. The reference to “microdendritic” was merely made to indicate a very small size, but this is in no way intended as a precise limitation on the size of the features formed by applicant’s invention.

The Examiner noted that claim 2 recites “the pad surface” on line 1, and yet more than one “pad” is recited.

The Examiner is thanked for the suggested change, and this has been accomplished.

The Examiner also noted that claim 3 is confusing as to what a “seed” is, and that in view of claim 5 the “seed” is the copper 24, but the specification also seems to call the Ta a “seed”.

From the change made in response to the Examiner's comment of claim 3 being confusing as to what the "seed" is, it will now be perfectly clear that the seed layer is the layer 24 of copper. The Examiner is thanked for noting this need for change.

As to Examiner's noting that claim 13 recites "the step", this has been changed to "a step" as suggested. Likewise, claim 14 now has been changed to state "a step" instead of "the step".

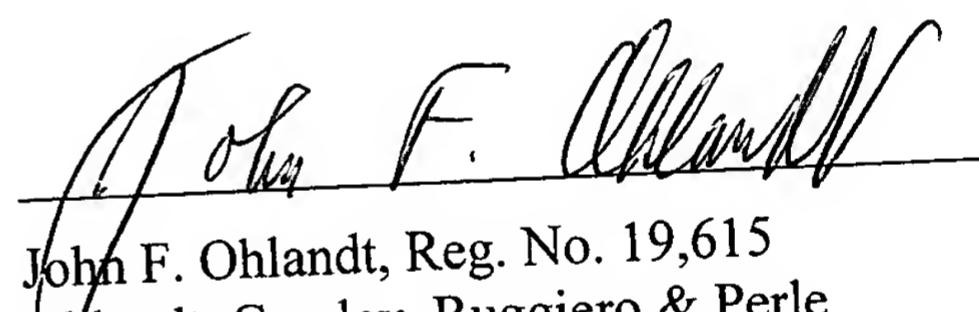
The Examiner also indicated that claims 14 and 18 recite a limitation of "the receptacles" and that there is insufficient antecedent basis for this limitation.

Accordingly, the independent claim 12 has been amended to include "a plurality of receptacles on the carrier."

It is respectfully submitted that this application is now in condition to be passed to issue.

Respectfully submitted,

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